



Material Content Data Sheet



Sales Product Name		TLE9272QX		Issued		31. January 2019		
MA#		MA004737234						
Package		PG-VQFN-48-31		Weight*		129.77 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.989	3.07	3.07	30741	30741
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		552	
	non noble metal	iron	7439-89-6	1.433	1.10		11044	
wire	non noble metal	copper	7440-50-8	58.193	44.85	46.02	448450	460184
	non noble metal	copper	7440-50-8	0.596	0.46	0.46	4596	4596
encapsulation	organic material	carbon black	1333-86-4	0.184	0.14		1414	
	plastics	epoxy resin	-	7.770	5.99		59879	
	inorganic material	silicondioxide	60676-86-0	53.229	41.02	47.15	410198	471491
leadfinish	non noble metal	tin	7440-31-5	2.596	2.00	2.00	20009	20009
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4730	4730
glue	plastics	epoxy resin	-	0.246	0.19		1897	
	noble metal	silver	7440-22-4	0.824	0.64	0.83	6352	8249
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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